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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

WHAT IS CLAIMED IS:

Claims 1-30. (Cancelled)

31. (Currently Amended) A method for cleaning a substrate surface on a moving conveyor, comprising:

dry washing the substrate ~~to introduce~~ by introducing the substrate into a mixed atmosphere of an inert gas and water vapor under irradiation of ultraviolet light from a dielectric barrier discharge lamp;

decomposing organic substances deposited on the surface of the substrate with the dielectric barrier discharge lamp while splitting water vapor into a reducing active member [H •] and an oxidative active member [• OH] ~~to cause reactions with the decomposition of, the active member [H •] and oxidative active member [• OH] react with the decomposed the organic substances by means of the reducing and oxidative members [H •] and [• OH] to cause the decomposed organic substances to be removed from the surface of the substrate;~~

wet washing ~~step~~ the substrate to remove inorganic contaminants by supplying washing water on the surface of the substrate; and

drying the substrate to eliminate washing water from the substrate surface.

32. (Currently Amended) A method for applying a liquid developer on a substrate surface on a moving conveyor, comprising:

wet washing the substrate by supplying washing water to the surface of the substrate;

drying the substrate to eliminate washing water from the substrate surface;

placing the substrate in a mixed atmosphere of an inert gas and water to ~~improve~~ reduce the contact angle of the substrate surface ~~and thus improving the surface of the substrate~~, the inert gas and water vapor being under irradiation of ultraviolet light from a dielectric barrier discharge lamp to decompose organic substances deposited on a surface of the substrate while splitting water vapor into a reducing active member [$H \cdot$] and an oxidative active member [$\cdot OH$];

subjecting the reducing and oxidative members [$H \cdot$] and [$\cdot OH$] to ~~reactions with decomposition products of the~~ cause a reaction with the decomposed organic substances; and

coating the surface of the substrate with a liquid developer.